

CLAIM AMENDMENTS

1 - 29. (canceled)

1 30. (currently amended) A method of making [[an]]
2 electronic components each having a chip module with module
3 contacts and an antenna having antenna contacts, the method
4 comprising the steps of:

5 securing a plurality of the chip modules ~~and module~~
6 ~~contacts~~ to the inner face of an elongated module film strip having
7 an outer periphery projecting past the chip module ~~and module~~
8 ~~contacts~~ with the chip modules spaced from one another on the
9 module film strip at a uniform predetermined module spacing;

10 securing a plurality of the antennas ~~and antenna contacts~~
11 to an inner face of ~~a support~~ an elongated antenna strip with the
12 antennas spaced from one another by a predetermined distance that
13 is substantially greater than the module spacing;

14 releasably adhering a mounting strip to an outer face of
15 the antenna strip;

16 longitudinally subdividing the film strip into film
17 sections each of which is of a length equal to the predetermined
18 module spacing and each of which carries a respective chip module;

19 pressing the module film sections against the support
20 antenna strip such that the module contacts of each of the chip

21 modules engage and bear on the antenna contacts of a respective
22 antenna; and
23 bonding the outer periphery of each of the film sections
24 to the inner face of the support antenna strip generally all around
25 each the chip modules.

1 31. (previously presented) The method defined in claim
2 30 wherein the contacts of the chip module or of the antenna have
3 points so that when pressed against the other contacts they
4 penetrate the other contacts.

1 32. (previously presented) The method defined in claim
2 31 wherein the pointed contacts are of pyramidal shape.

1 33. (previously presented) The method defined in claim
2 32 wherein each pointed contact is formed by a multiplicity of
3 particles.

1 34. (previously presented) The method defined in claim
2 33 wherein the particles are nickel-coated diamond particles.

35 - 37. (canceled)

1 38. (currently amended) The method defined in claim
2 [[37]] 30 wherein the longitudinal subdivision of the module film

3 ~~strip carrying the modules~~ is carried out before pressing the film
4 sections against the respective antennas on ~~[[its]]~~ the antenna
5 strip.

1 39. (currently amended) The method defined in claim 38,
2 further comprising the step, after longitudinally subdividing the
3 module film strip carrying the modules, of
4 longitudinally spacing the film sections by the antenna
5 spacing distance.

1 40. (currently amended) The method defined in claim
2 ~~[[37]]~~ 30, wherein the strip sections carrying the modules ~~[[is]]~~
3 are pressed against the antenna strip carrying the antennas before
4 longitudinally subdividing the module film strip, the longitudinal
5 subdivision of the module film strip ~~carrying the modules~~ being
6 carried out by removing pieces of the module film strip between
7 succeeding modules.

1 41. (currently amended) The method defined in claim
2 ~~[[37]]~~ 30, further comprising the step of
3 coating the antenna strip with adhesive prior to pressing
4 the ~~module strip~~ film sections and their respective modules against
5 the antenna strip.

1 42. (previously presented) The method defined in claim
2 41 wherein the coating with adhesive is only done to discrete
3 regions of the antenna strip adjacent the antenna contacts.

1 43. (previously presented) The method defined in claim
2 42 wherein the discrete regions have a size generally corresponding
3 to the module spacing.

1 44. (currently amended) The method defined in claim
2 [[37]] 30, further comprising the steps of
3 releasably mounting the module film strip on a mounting
4 strip;
5 separating the mounting strip from the module film strip
6 prior to securing thereto the modules ~~and module contacts~~; and
7 releasably securing the modules directly to the mounting
8 strip at least after longitudinal subdivision of the module film
9 strip.

1 45. (currently amended) The method defined in claim 44
2 wherein the modules are releasably secured to the mounting strip
3 before longitudinal subdivision of the module film strip and the
4 longitudinal subdivision of the module film strip is carried out by
5 removing pieces of the module film strip between the modules.

1 46. (currently amended) The method defined in claim 37,
2 further comprising the step of
3 rolling up the antenna strip after pressing the ~~module~~
4 film sections against the antenna strip ~~forming the support~~.

1 47. (previously presented) The method defined in claim
2 46, further comprising the step prior to rolling up the antenna
3 strip of
4 inspecting the modules.

1 48. (currently amended) The method defined in claim 47,
2 further comprising the step_L after inspecting the modules_L of
3 marking any modules failing inspection.

49. (canceled)

1 50. (currently amended) The method defined in claim
2 [[37]] 30, further comprising the step of
3 releasably adhering a mounting strip to outer faces of
4 the ~~module~~ strip sections turned away from the antenna strip and to
5 exposed portions of the ~~face of the~~ antenna strip between adjacent
6 film sections.

1 51. (previously presented) The method defined in claim
2 30 wherein the module is associated with two respective module
3 contacts and the module is secured to the film between the two
4 respective contacts.

1 52. (currently amended) The method defined in claim 30
2 wherein the ~~module~~ film strip is flexible and of plastic.